TOSHIBA PHOTOCOUPLER PHOTO RELAY

TLP3131

MEASUREMENT INSTRUMENTS LOGIC IC TESTERS / MEMORY TESTERS BOARD TESTERS / SCANNERS

The TOSHIBA TLP3131 Mini-flat photorelay is a small-outline photorelay, suitable for surface-mount assembly. The TLP3131 consists of an infrared-emitting diode optically coupled to a photo-MOS FET and housed in a 4-pin package.

The TLP3131 features low CR product and especially low ON-state resistance, allowing high ON-state current.

Its characteristics also include low OFF-state current and low output pin capacitance, enabling it to be used in high-frequency measuring instruments.

Features

• 4 pin SOP (2.54SOP4) : 2.1 mm high, 2.54 mm pitch

• 1-Form-A

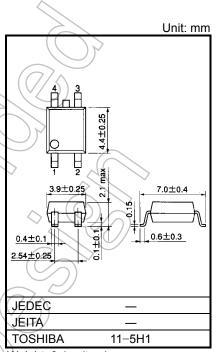
Peak Off-State Voltage : 20 V (min)
 Trigger LED Current : 4 mA (max)
 On-State Current : 300 mA (max)

On-State Resistance
 1.5 Ω (max), 1.0 Ω (typ.)
 Output Capacitance
 12.0 pF (max), 5.0 pF (typ.)

• Isolation Voltage : 1500 Vrms (min)

• UL-recognized : UL 1577, File No.E67349

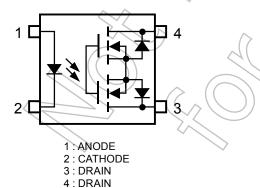
CSA Component Acceptance Service No.5A
File No.E67349

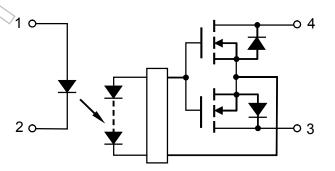


Weight: 0.1 g (typ.)

p view) Schematic

Pin Configuration (top view)





Start of commercial production 2001-03

Absolute Maximum Ratings (Ta = 25°C)

	CHARACTERISTIC	SYMBOL	RATING	UNIT
	Forward Current	lF	50	mA
	Forward Current Derating (Ta ≥ 25°C)	ΔI _F /°C	-0.5	mA/°C
٥	Reverse Voltage	V _R	5	V
LE	Diode Power Dissipation	P_D	50	mW
	Diode Power Dissipation Derating (Ta ≥ 25°C)	ΔP_D /°C	-0.5	mW/°C
	Junction Temperature	Tj	125	°C
DETECTOR	Off-State Output Terminal Voltage	Voff	20	(V)/
	On-State Current	Ion	300	mA
	On-State Current Derating (Ta ≥ 25°C)	Δlon/°C	-3.0	mA/°C
	Output Power Dissipation	Po	135	mW
	Output Power Dissipation Derating (Ta ≥ 25°C)	ΔP _o /°C	-1.35	mW / °C
	Junction Temperature	Tj	125	°C
Stora	ge Temperature Range	T _{stg}	-40 to 125	°C
Oper	ating Temperature Range	Topr	-20 to 85	© \(\)
Lead	Soldering Temperature (10 s)	T _{sol}	260	°C
Isolat	tion Voltage (AC, 60 s, R.H. ≤ 60 %) (Note 1)	BVs	1500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Device considered a two-terminal device. Pins 1 and 2 shorted together, and pins 3 and 4 shorted together.

Caution

This device is sensitive to electrostatic discharge. When using this device, please ensure that all tools and equipment are earthed.

Recommended Operating Conditions

CHARACTERISTIC	SYMBOL	ME	TYP.	MAX	UNIT
Supply Voltage	VDD	> —	_	20	V
Forward Current	JF.	10	_	30	mA
On-State Current	ION	_	_	300	mA
Operating Temperature	T _{opr}	25	_	60	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Individual Electrical Characteristics (Ta = 25°C)

	CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
	Forward Voltage	VF	I _F = 10 mA	1.0	1.15	1.3	V
LED	Reverse Current	IR	V _R = 5 V	ı	l	10	μА
	Capacitance between terminals	CT	V _F = 0 V, f = 1 MHz		15		pF
CTOR	Off-State Current	l _{OFF}	V _{OFF} = 20 V, Ta = 50 °C	ı	ı	1000	pА
DETECTOR	Capacitance between terminals	COFF	V = 0 V, f = 100 MHz, t < 1 s	ı	5.0	12.0	pF

Coupled Electrical Characteristics (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Trigger LED Current	I _{FT}	I _{ON} = 100 mA	_	_	4	mA
Return LED Current	I _{FC}	I _{OFF} = 10 μA	0.2	0.75	_	mA
On-State Resistance	Ron	I _{ON} = 300 mA, I _F = 5 mA, t < 1 s	7/	1	1.5	Ω

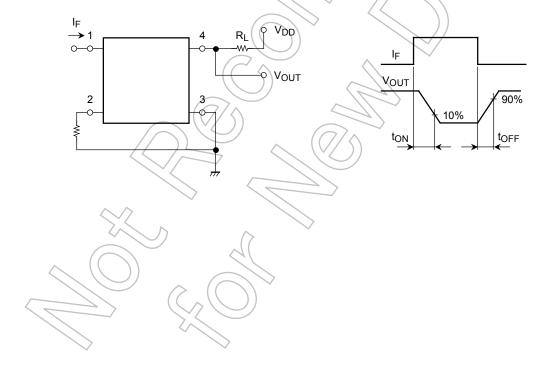
Isolation Characteristics (Ta = 25°C)

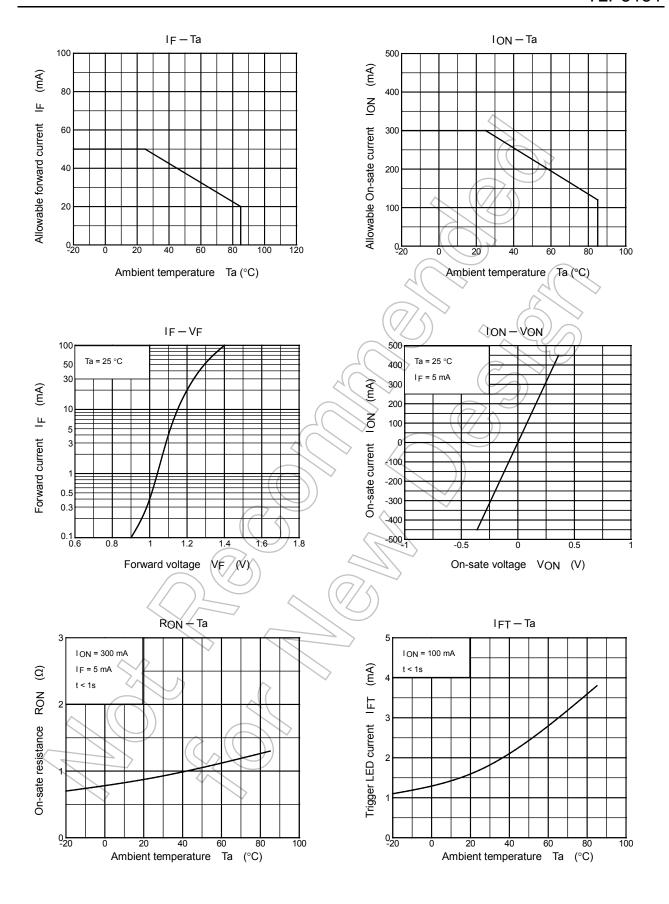
CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN	TYP.	MAX	UNIT
Capacitance Input to Output	Cs	V _S = 0 V, f = 1 MHz	<u> </u>	0.8	_	pF
Isolation Resistance	Rs	V _S = 500 V, R.H. ≤ 60 %	5 × 10 ¹⁰	10 ¹⁴	_	Ω
Isolation Voltage	BVs	AC, 60 s	1500	4	\ <u>\</u>	Vrms

Switching Characteristics (Ta = 25°C)

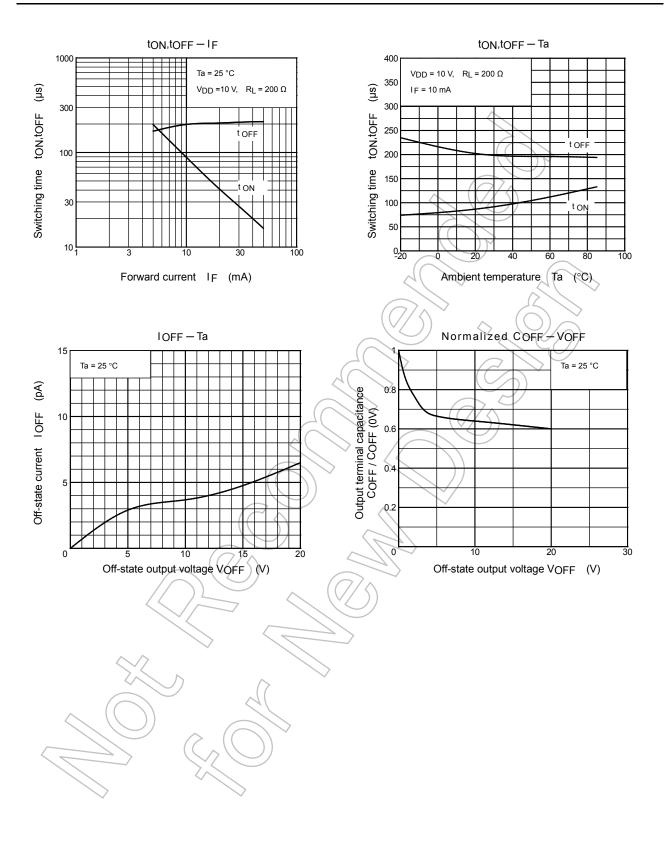
CHARACTERISTIC	SYMBOL	TEST CONDITION	MJN	TYP.	MAX	UNIT
Turn-on Time	ton	$R_L = 200 \Omega$ (NOTE 2)) —	500	0
Turn-off Time	toff	$V_{DD} = 10 \text{ V, IF} = 10 \text{ mA}$	7< \	_	500	μS

NOTE 2: SWITCHING TIME TEST CIRCUIT





NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



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